

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

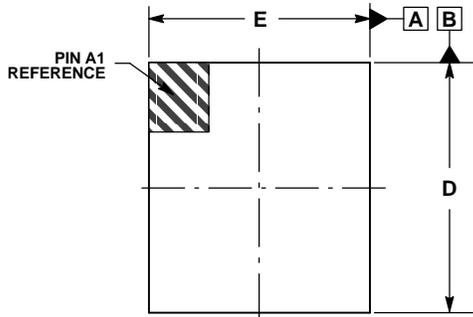
ON Semiconductor®



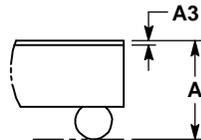
SCALE 4:1

WLCSP31, 2.77x2.45
CASE 567NB
ISSUE A

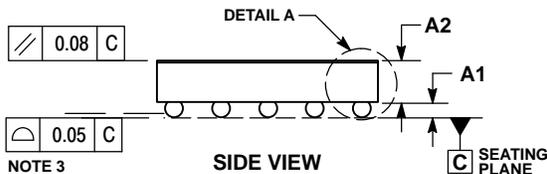
DATE 23 JUN 2016



TOP VIEW

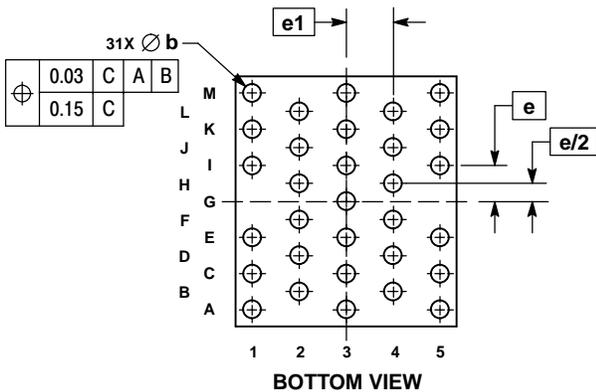


DETAIL A



SIDE VIEW

NOTE 3



BOTTOM VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF THE SOLDER BALLS.
4. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM BALL DIAMETER PARALLEL TO DATUM C.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	---	---	0.635
A1	0.17	0.20	0.23
A2	0.405 REF		
A3	0.025 REF		
b	0.20	0.225	0.25
D	2.74	2.77	2.80
E	2.42	2.45	2.48
e	0.40 BSC		
e1	0.52 BSC		

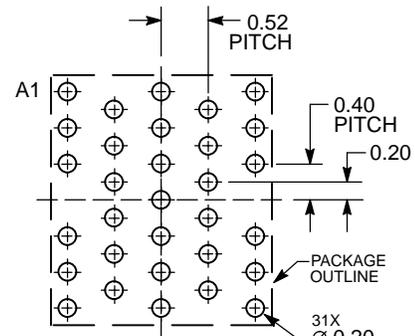
GENERIC MARKING DIAGRAM*



- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	WLCSP31, 2.77X2.45	PAGE 1 OF 2

